



Specs

Orderable Parts for: MT29C4G48MAYBBAKS-48 IT

	Status	Media	FBGA Code	SPD Data	Chipset Validation	PLP	Start Date	Alternative Part
MT29C4G48MAYBBAKS-48 IT	Production	N/A	JWB09	N/A	N/A	No		N/A

SEE ALL NAND-BASED MCP PARTS

Detailed Specifications

Part Status Code	Production	NAND Density	4Gb	DRAM Type	LPDDR	DRAM Density	2Gb
Bus Width	x8	Secondary Bus Width	x16	RoHS	Yes	Voltage	1.7V-1.9V
Package Downloaded from Arrov	VFBGA v.com.	Pin Count	137-ball	Clock Rate	208 MHz	Operating Temp	-40C to +85C

Sim Models & Software

Sim Models





IBIS_J4Q2_FBGA130, FBGA137, FBGA168 (ZIP)

4Gb: x8, x16 NAND Flash with 2Gb: x32 LPDDR MCP

File Type: ZIP

Updated: 03/15/2016

Multichip Packages NAND LPDDR

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RoHS Certificates

RoHS Certificates

RoHS Certificate of Compliance (PDF)

Part-specific certification of how this product meets the requirements of the current DIRECTIVE 2002/95/EC, a.k.a. Restriction of Hazardous Substances (RoHS) Directive.

File Type: (PDF)

Updated: 04/2017

MT29C4G48MAYBBAKS-48 IT

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RoHS Certificates

China RoHS Certificate (PDF)

Part-specific certification as required by China's Management Methods for Controlling Pollution by Electronic Information Products.

File Type: (PDF)

Updated: 04/2017

MT29C4G48MAYBBAKS-48 IT

Documentation & Support

See All NAND-Based MCP Documentation

Technical Notes

SEARCH (2) NAND-BASED MCP TECHNICAL NOTES

Technical Notes

TN-00-01: Moisture Sensitivity of Plastic Packages (PDF)

(TN-00-01) This technical note describes shipping procedures for preventing memory devices from absorbing moisture and recommendations for baking devices exposed to excessive moisture.

DDR2 SDRAM DDR3 SDRAM DDR3L-RS

DDR SDRAM

See More Tags

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File Type: PDF

Updated: 02/14/2013

Technical Notes

TN-10-08: Thermal Implications for LPDDR Die Stacks (PDF)

Mobile Memory Solutions Multichip Packages NAND-Based MCP

(TN-10-08) This technical note presents a case study of a handset simulation in which an LPDRAM is stacked on an application processor (PoP) and the resulting thermal-profile modeling. This note also explains how thermal detection features included in LPDDR and LPDDR2 can be used to...

File Type: PDF

Updated: 07/26/2010

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SEARCH (2) NAND-BASED MCP TECHNICAL NOTES

Customer Service Note

Customer Service Note

Customer Service Note

Micron Component and Module Packaging (PDF)

Big Data Big Data Client SSD Storage Cloud See More Tags

(CSN-16) Explanation of Micron packaging labels and procedures.

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File Type: PDF **Updated:** 03/22/2017

Customer Service Note

PoP User Guide (PDF)

Multichip Packages NAND-Based MCP

(CSN-34) Provides several well-established guidelines for package-on-package (PoP) semiconductor package design and assembly, which requires unique considerations in both the up-front design and the manufacturing process.

File Type: PDF

Updated: 05/16/2016

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SEARCH (2) NAND-BASED MCP CUSTOMER SERVICE NOTE

Parts with the same Data Sheet (2)

MT29C4G48MAYBBAKS-48 IT (Current)		MT29C4G48MAZBBAKS-48 IT	MT29C4G48MAYBBAHK-48 A IT	
Part Status Code	Production	Production	Production	
NAND Density	4Gb	4Gb	4Gb	
DRAM Type	LPDDR	LPDDR	LPDDR	
DRAM Density	2Gb	2Gb	2Gb	
Bus Width	х8	x16	x8	
Secondary Bus Width	x16	х32	x32	
RoHS	Yes	Yes	Yes	
Voltage	1.7V-1.9V	1.7V-1.9V	1.7V-1.9V	
Package	VFBGA	VFBGA	VFBGA	
Pin Count	137-ball	137-ball	137-ball	
Clock Rate	208 MHz	208 MHz	208 MHz	
Operating Temp	-40C to +85C	-40C to +85C	-40C to +85C	

MT29C4G48MAYBBAKS-48 IT

(Current)

Part Status Code	Production					
NAND Density	4Gb					
DRAM Type	LPDDR					
DRAM Density	2Gb					
Bus Width	х8					
Secondary Bus Width	x16					
RoHS	Yes					
Voltage	1.7V-1.9V					
Package	VFBGA					
Pin Count	137-ball					
Clock Rate	208 MHz					
Operating Temp	-40C to +85C					

Where to Buy

Status	Media	FBGA Code	SPD Data	Chipset Validation	PLP	Start Date	Alternative Part
Production	N/A	JWB09	N/A	N/A	No		N/A

- OR - Check with Distributors

Your Region: Americas



Downloaded from Arrow.com.

WDW



See All Distributors

Solutions

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DRAM Modules
NAND Flash

Managed NAND NOR Flash Hybrid Memory Cube Multichip Packages

Solid State Drives

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